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** CONTINUING DATA *****

This application is a CON of 10/031,000 01/16/2002 PAT 6,780,668
 which is a 371 of PCT/JP00/04699 07/13/2000

CME

** FOREIGN APPLICATIONS *****

JAPAN 11-202847 07/16/1999
 JAPAN 2000-63686 03/08/2000

CME

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 03/29/2004

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| Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no | STATE OR COUNTRY JAPAN | SHEETS DRAWING 35 | TOTAL CLAIMS 10 | INDEPENDENT CLAIMS 1 |
| 35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance | | | | |
| Verified and Acknowledged <i>Charles</i> Examiner's Signature | Initials | | | |

ADDRESS

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TITLE

Semiconductor device package manufacturing method and semiconductor device package manufactured by the method

☐ All Fees☐ 1.16 Fees (Filing)